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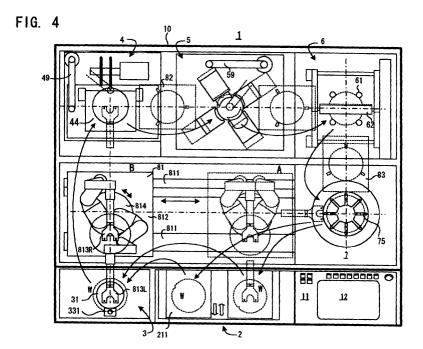
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## (54) Semiconductor wafer polishing apparatus and polishing method

(57) An object of the present invention is to unchange the order of wafers when passed through a wafer outer peripheral part polishing apparatus (1), thereby simplifying control for each wafer. In predetermined positions of a frame (10) of a wafer outer peripheral part polishing unit (5), there are arranged and attached a wafer cassette reception and discharge opening unit (2), a wafer position aligning unit (3), a wafer notch polishing

unit (4), a wafer circumferential part polishing unit (5), an inside carrier unit, a first slurry supply device (49), and a second slurry supply device (59). The inside carrier unit has a first carrier sub-unit (81), a second carrier sub-unit (82), and a third carrier sub-unit (83). After a wafer taken out from the wafer cassette reception and discharge opening unit (2) is polished, the wafer is returned to the same slot of the same cassette from which it is taken out. Thus, the order is not changed.





## **EUROPEAN SEARCH REPORT**

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Category	Citation of document with of relevant pas	indication, where appropriate, sages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.CI.7)
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## ANNEX TO THE EUROPEAN SEARCH REPORT ON EUROPEAN PATENT APPLICATION NO.

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For more details about this annex : see Official Journal of the European Patent Office, No. 12/82